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For Immediate Release

Seika Machinery to Kick Off SMI 2026 Webinar Series with Focus on Solder Paste Preparation and Control

TORRANCE, CA — June 2026 — Seika Machinery, Inc., a leading provider of advanced machinery, materials and engineering services, will kick off its SMI 2026 Webinar Series with Session 1, “*Solder Paste... Automating Preparation Practices*,” focusing on the early-stage process variables that often determine print quality and overall SMT stability. The first session will be held on Wednesday, June 24, 2026 at 1 p.m. Eastern Time (US and Canada).

Webinar Registration:
[Register for SMI 2026 Webinar Series Session 1](#)

Solder paste remains one of the most sensitive materials in surface mount assembly. Even small inconsistencies in mix, temperature, or handling can shift viscosity and directly impact stencil printing performance, defect rates, and downstream reflow results.

This session will look at what actually drives those variations and why controlling solder paste condition before it reaches the printer is becoming a higher priority for many manufacturers. That includes maintaining consistent mixing practices, controlling working temperature, and standardizing how paste is brought to print-ready condition after storage.

A key part of the discussion will focus on viscosity measurement and its role in validating paste readiness. Seika will highlight its Malcom viscometer systems, which are designed to measure both static and dynamic viscosity by applying controlled shear to the material. This approach is intended to better reflect real printing conditions and provide more reliable insight into how a paste will behave on the stencil rather than relying on static-only measurements.

The webinar will also cover automation opportunities in paste preparation, particularly where manual handling can introduce variation, and how process control tools can help standardize what has traditionally been a highly operator-dependent step.

“In many SMT environments, paste issues don’t show up at the mixer, they show up at the printer,” said Michelle Ogihara, Executive VP, Seika Machinery. “The goal is to remove as much variability as possible before it gets that far.”





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By tying together mixing practices, temperature control, and viscosity verification, the session is designed to give manufacturers a clearer path toward more consistent print performance and fewer downstream surprises.

The SMI 2026 Webinar Series is aimed at practical, shop-floor-focused improvements rather than theoretical discussion, with an emphasis on repeatable process control in real production environments.

To learn more, visit [SMT Process Control Equipment | Seika Machinery Inc.](#)

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About Seika Machinery, Inc.

Seika Machinery, Inc. (SMI) is a subsidiary of Seika Corporation, Japan and member of the Mitsubishi Global Group. SMI provides electronics manufacturers with advanced machinery, superior materials and engineering services.